

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Extended Temperature Performance of –40°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree[†]**
- **Member of the Texas Instruments Widebus™ Family**
- **Inputs Are TTL-Voltage Compatible**
- **3-State Outputs Drive Bus Lines Directly**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise**

[†] Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, highly accelerated stress test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life.

description

The SN74ACT16245Q-EP is a 16-bit bus transceiver organized as dual-octal noninverting 3-state transceivers and designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The enable ($\overline{G}$) input can be used to disable the devices so that the buses are effectively isolated.

DL PACKAGE
(TOP VIEW)

1DIR	1	48	1 $\overline{G}$
1B1	2	47	1A1
1B2	3	46	1A2
GND	4	45	GND
1B3	5	44	1A3
1B4	6	43	1A4
V _{CC}	7	42	V _{CC}
1B5	8	41	1A5
1B6	9	40	1A6
GND	10	39	GND
1B7	11	38	1A7
1B8	12	37	1A8
2B1	13	36	2A1
2B2	14	35	2A2
GND	15	34	GND
2B3	16	33	2A3
2B4	17	32	2A4
V _{CC}	18	31	V _{CC}
2B5	19	30	2A5
2B6	20	29	2A6
GND	21	28	GND
2B7	22	27	2A7
2B8	23	26	2A8
2DIR	24	25	2 $\overline{G}$

ORDERING INFORMATION

T _A	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SSOP – DL	Tape and reel	SN74ACT16245QDLREP	ACT16245QEP

[‡] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

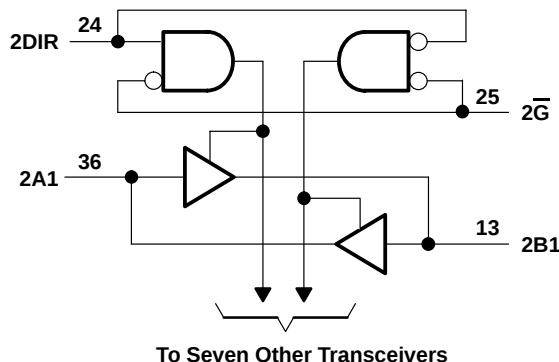


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SCAS677A – MAY 2002 – REVISED JULY 2002

CONTROL INPUTS		OPERATION
$\overline{G}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation



Supply voltage range, V_{CC}	−0.5 V to 7 V
Input voltage range, V_I (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Note 1)	−0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±24 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±24 mA
Continuous current through V_{CC} or GND	±260 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 2): DL package	1.2 W
Storage temperature range, T_{stg}	−65°C to 150°C

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
V _{CC}	Supply voltage (see Note 4)	4.5	5.5	V
V _{IH}	High-level input voltage	2		V
V _{IL}	Low-level input voltage		0.8	V
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current		–16	mA
I _{OL}	Low-level output current		16	mA
Δt/Δv	Input transition rise or fall rate	0	10	ns/V
T _A	Operating free-air temperature	–40	125	°C

- NOTES: 3. Unused inputs should be tied to V_{CC} through a pullup resistor of approximately 5 kΩ or greater to keep them from floating. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
4. All V_{CC} and GND pins must be connected to the proper-voltage power supply.

SN74ACT16245Q-EP

16-BIT BUS TRANSCEIVER

WITH 3-STATE OUTPUTS

SCAS677A – MAY 2002 – REVISED JULY 2002

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	T _A = 25°C			MIN	MAX	UNIT
				MIN	TYP	MAX			
V _{OH}		I _{OH} = –50 µA	4.5 V	4.4			4.4		V
			5.5 V	5.4			5.4		
		I _{OH} = –16 mA	4.5 V	3.94			3.94		
			5.5 V	4.94			4.94		
		I _{OH} = –24 mA†	5.5 V				3.85		
V _{OL}		I _{OL} = 50 µA	4.5 V			0.1		0.1	V
			5.5 V			0.1		0.1	
		I _{OL} = 16 mA	4.5 V			0.36		0.5	
			5.5 V			0.36		0.5	
		I _{OL} = 24 mA†	5.5 V					0.5	
I _I	Control inputs	V _I = V _{CC} or GND	5.5 V			±0.1		±1	µA
I _{OZ}	A or B ports‡	V _O = V _{CC} or GND	5.5 V			±0.5		±10	µA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	5.5 V			8		160	µA
ΔI _{CC} §		One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			0.9		1	mA
C _i	Control inputs	V _I = V _{CC} or GND	5 V		4.5				pF
C _{io}	A or B ports	V _O = V _{CC} or GND	5 V		16				pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

‡ For I/O ports, the parameter I_{OZ} includes the input leakage current I_I.

§ This is the increase in supply current for each input that is at one of the specified TTL-voltage levels rather than 0 V or V_{CC}.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

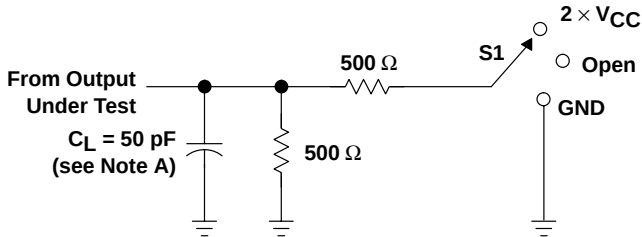
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t _{PLH}	A or B	B or A	3.2	6.9	9.3	3.2	11.5	ns
t _{PHL}			2.6	6.4	9.2	2.6	11.1	
t _{PZH}	$\overline{G}$	B or A	2.7	6.4	9.1	2.7	10.9	ns
t _{PZL}			3.4	7.4	10.5	3.4	12.6	
t _{PHZ}	$\overline{G}$	B or A	5.8	9.2	11.6	5.8	13.4	ns
t _{PLZ}			5.5	8.5	10.8	5.5	12.7	

operating characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	Outputs enabled	C _L = 50 pF, f = 1 MHz	52	pF
		Outputs disabled		10	

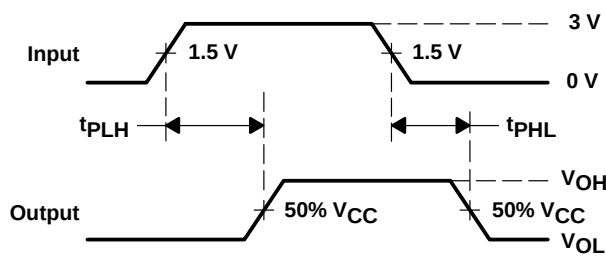


PARAMETER MEASUREMENT INFORMATION

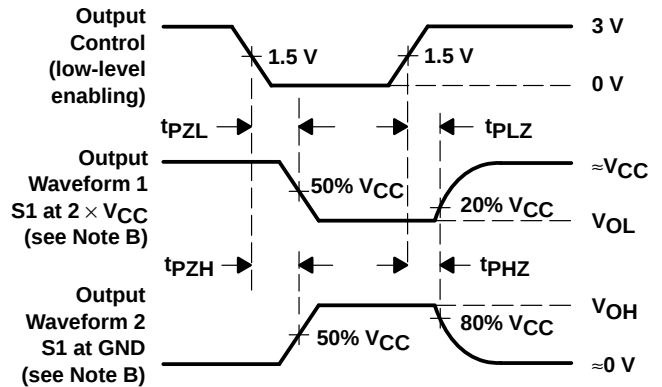


LOAD CIRCUIT

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 $\times V_{CC}$
t_{PHZ}/t_{PZH}	GND



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

- NOTES: A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$.
- D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ACT16245QDLREP	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03601-01XE	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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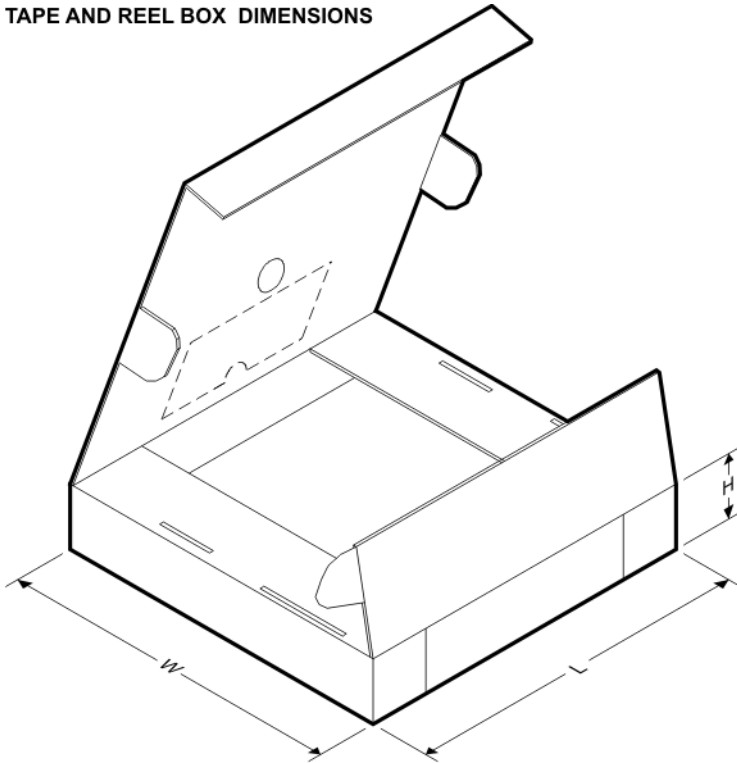
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT16245QDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



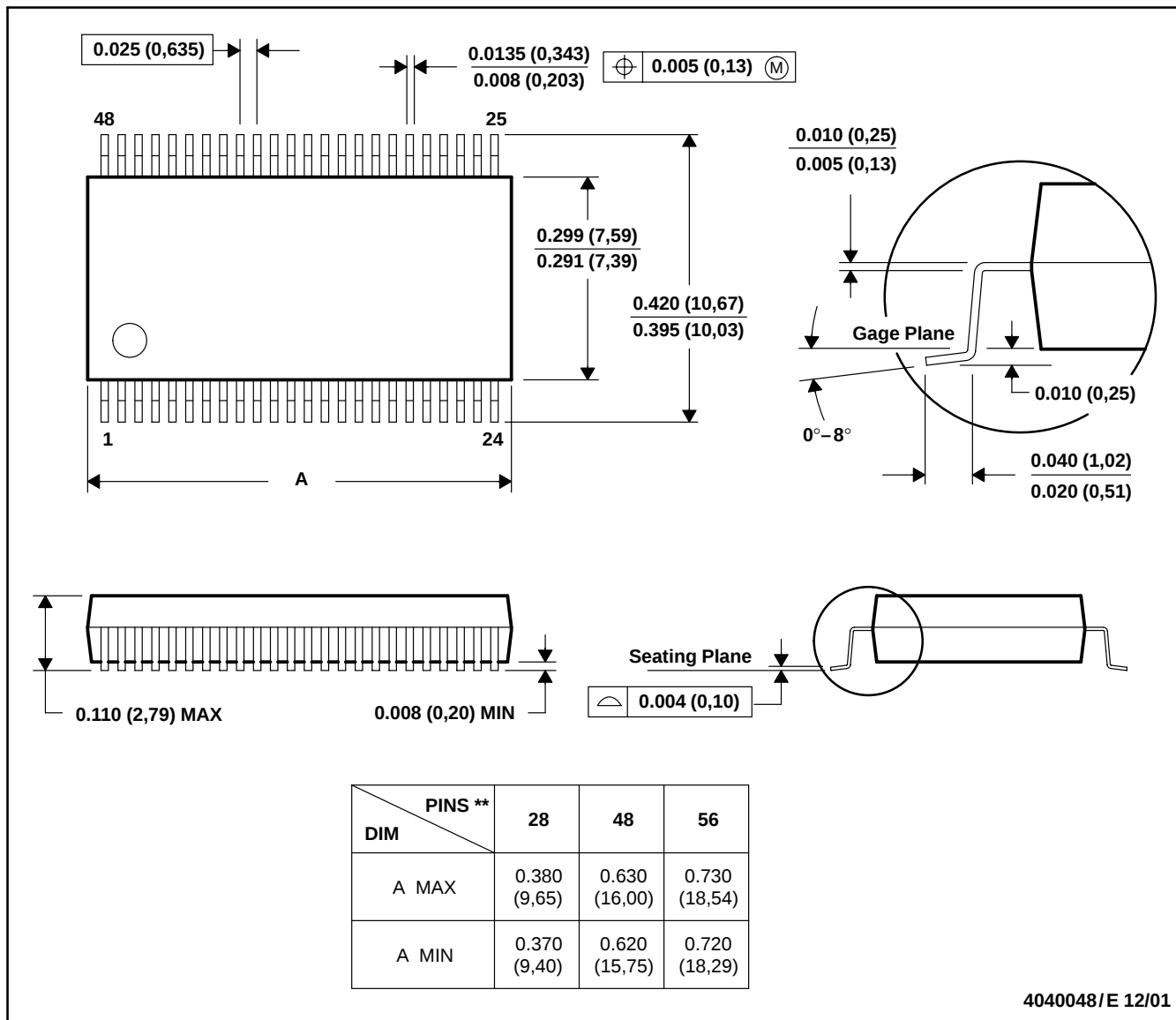
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT16245QDLREP	SSOP	DL	48	1000	346.0	346.0	49.0

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
74ACT16245QDLREPG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT16245QEP	Samples
SN74ACT16245QDLREP	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT16245QEP	Samples
V62/03601-01XE	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	ACT16245QEP	Samples

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TBD: The Pb-Free/Green conversion plan has not been defined.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT16245QDLREP	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



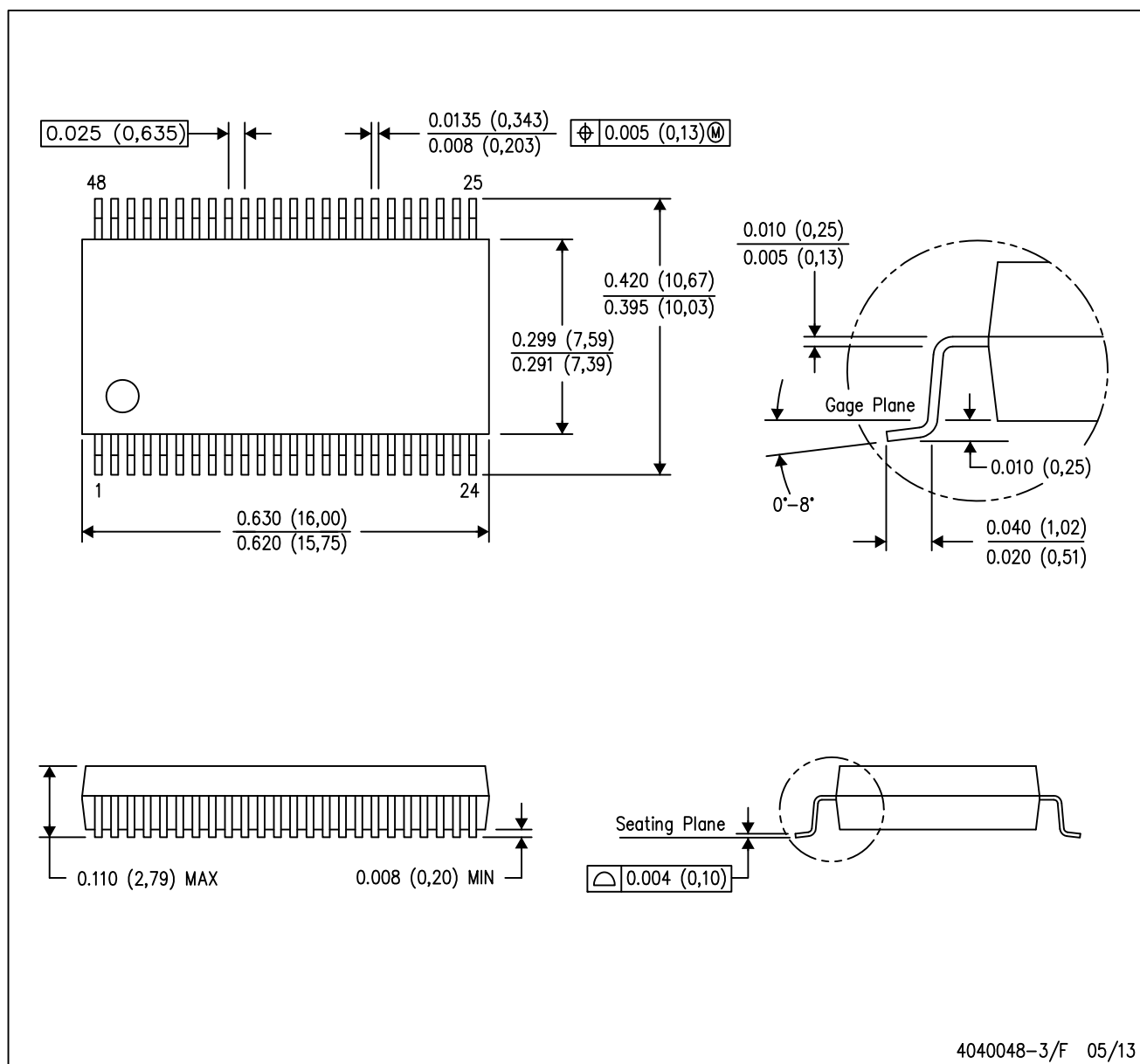
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT16245QDLREP	SSOP	DL	48	1000	367.0	367.0	55.0

MECHANICAL DATA

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
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D. Falls within JEDEC MO-118

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